



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-01-02
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U073CBU6	72MI*489XXXA	A	998Z	2024-01-02
Amount	Unit of measure	Unit type	ST ECOPACK grade	
102	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	7x7	48	Flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	72MI*489XXXA		101.6085		600000.0	100000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.109	mg	supplier	die	Silicon (Si)	7440-21-3		1.708	mg	809653	16806				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	9383	195				
				supplier	metallization	Copper (Cu)	7440-50-8		0.170	mg	80429	1669				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.055	mg	26139	543				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	670	14				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	670	14				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.044	mg	20777	431				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.110	mg	52279	1085				
				Glue epoxy (EN4900GC)	M-011 Other inorganic materials	0.307	mg	supplier	Organic Compounds	Acrylic resin	Proprietary		0.021	mg	70000	211
								supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.006	mg	20000	60
supplier	Organic Compounds	Butadiene copolymer	Proprietary						0.005	mg	15000	45				
supplier	Organic Compounds	Acrylate	Proprietary						0.017	mg	54000	163				
supplier	Organic Compounds	Epoxy resin	Proprietary						0.009	mg	30000	91				
supplier	Organic Compounds	Peroxide	Proprietary						0.002	mg	8000	24				
supplier	Organic Compounds	Additive	Proprietary						0.006	mg	18000	54				
supplier	Metals	Silver (Ag)	7440-22-4						0.241	mg	785000	2372				
Mold Compound (EME-G770)	M-011 Other inorganic materials	37.040	mg	supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.778	mg	21000	7655				
				supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.778	mg	21000	7655				
				supplier	Organic Compounds	Phenol Resin A	Proprietary		0.778	mg	21000	7655				
				supplier	Glass	Silica(Amorphous)A	60676-86-0		28.908	mg	780450	284504				
				supplier	Glass	Silica(Amorphous)B	7631-86-9		4.271	mg	115320	42039				
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.231	mg	6230	2271				
				supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.519	mg	14000	5104				
				supplier	Organic Compounds	Phenol Resin B	Proprietary		0.778	mg	21000	7655				
Bonding Wire (Au)	Bonding Wire	0.974	mg	supplier	Metals	Gold (Au)	7440-57-5		0.974	mg	1000000	9585				
Plating (Sn)	M-011 Other inorganic materials	1.078	mg	supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	10613				
Leadframe (C7025 + Ag)	Copper & its alloys	60.100	mg	supplier	Metals	Copper (Cu)	7440-50-8		55.120	mg	917140	542476				
				supplier	Metals	Nickel (Ni)	7440-02-0		1.352	mg	22500	13308				
				supplier	Metals	Silicon (Si)	7440-21-3		0.156	mg	2600	1538				
				supplier	Metals	Magnesium (Mg)	7439-95-4		0.069	mg	1150	680				
				supplier	Metals	Silver (Ag)	7440-22-4		3.402	mg	56610	33484				